
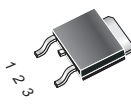


HAOPIN MICROELECTRONICS CO.,LTD.

Description

Glass passivated, sensitive gate thyristors in a plastic envelope, intended for use in general purpose switching and phase control applications. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

Symbol		Simplified outline	
		 TO-252	
Pin	Description		
1	Cathode		
2	anode		
3	gate		
TAB	anode		

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 6 A
- ◆ Ultra low gate trigger current

SYMBOL	PARAMETER	Value	Unit
V_{DRM}	Repetitive peak off-state voltages	600	V
$I_T (RMS)$	RMS on-state current (full sine wave)	6	A
I_{TAV}	Average on-state current	3.8	A

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Rth j-mb	Thermal resistance Junction to mounting base		-	-	2.0	K/W
Rth j-a	Thermal resistance Junction to ambient	In free air	-	70	-	K/W

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Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN	Value	UNIT
V_{RRM}	Repetitive peak reverse voltage		-	600	V
$I_{T(RMS)}$	RMS on-state current		-	6	A
I_{GM}	Peak gate current		-	2	A
I^2t	I^2t for fusing	RMS surge (non-repetitive) on-state current for period of 8.3ms for fusing	-	41	A ² s
I_{TSM}	Peak one-cycle forward surge current	60Hz	-	100	A
		50Hz	-	83	A
$P_{G(AV)}$	Average gate power dissipation		-	0.5	W
P_{GM}	Peak gate power dissipation		-	20	W
T_q	Circuit commutated turn-off time		-	35	μ s
T_{tg}	Gate controlled turn-on time; gate pulse=100mA; minmum width=15 μ s with rise time=<0.1 μ s		-	20	μ s

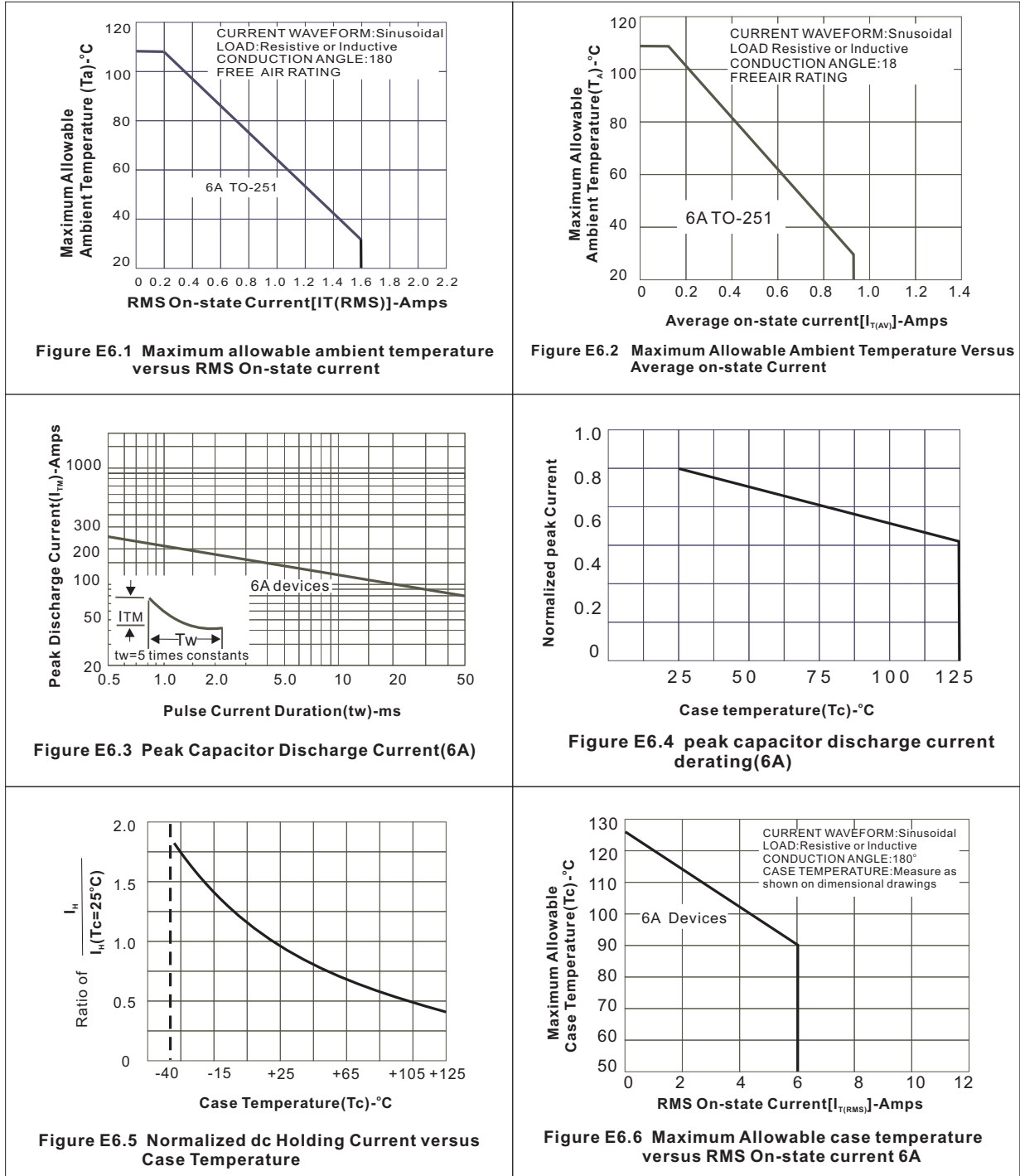
$T_j=25^\circ\text{C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Static characteristics						
I_{GT}	Dc gate trigger current	$V_D=12V, R_L=60\ \Omega$	-	-	200	μ A
V_{GT}	DC gate trigger voltage	$V_D=12V$ dc, $R_L=60\ \Omega$	-	-	1.5	V
DI/Dt	Maximum rate-of-rise of on-state current;	$I_{GT}=150mA$ with $\leq 0.1\ \mu$ s rise time,	-	-	100	A/ μ s
V_{TM}	On-state voltage	$T_a=25^\circ\text{C}, I_{TM}=0.6A$, instantaneous value	-	-	1.6	V
I_H		$V_D=12V; I_{GT}=0.1A$	-	-	6	mA
I_{DRM}	Peak off-state forward and reverse current at V_{DRM} and V_{RRM}	$T_c=125^\circ\text{C}, V_{DRM}$	-	-	0.5	mA
I_{RRM}		$T_c=125^\circ\text{C}, V_{RRM}$	-	-	0.5	mA

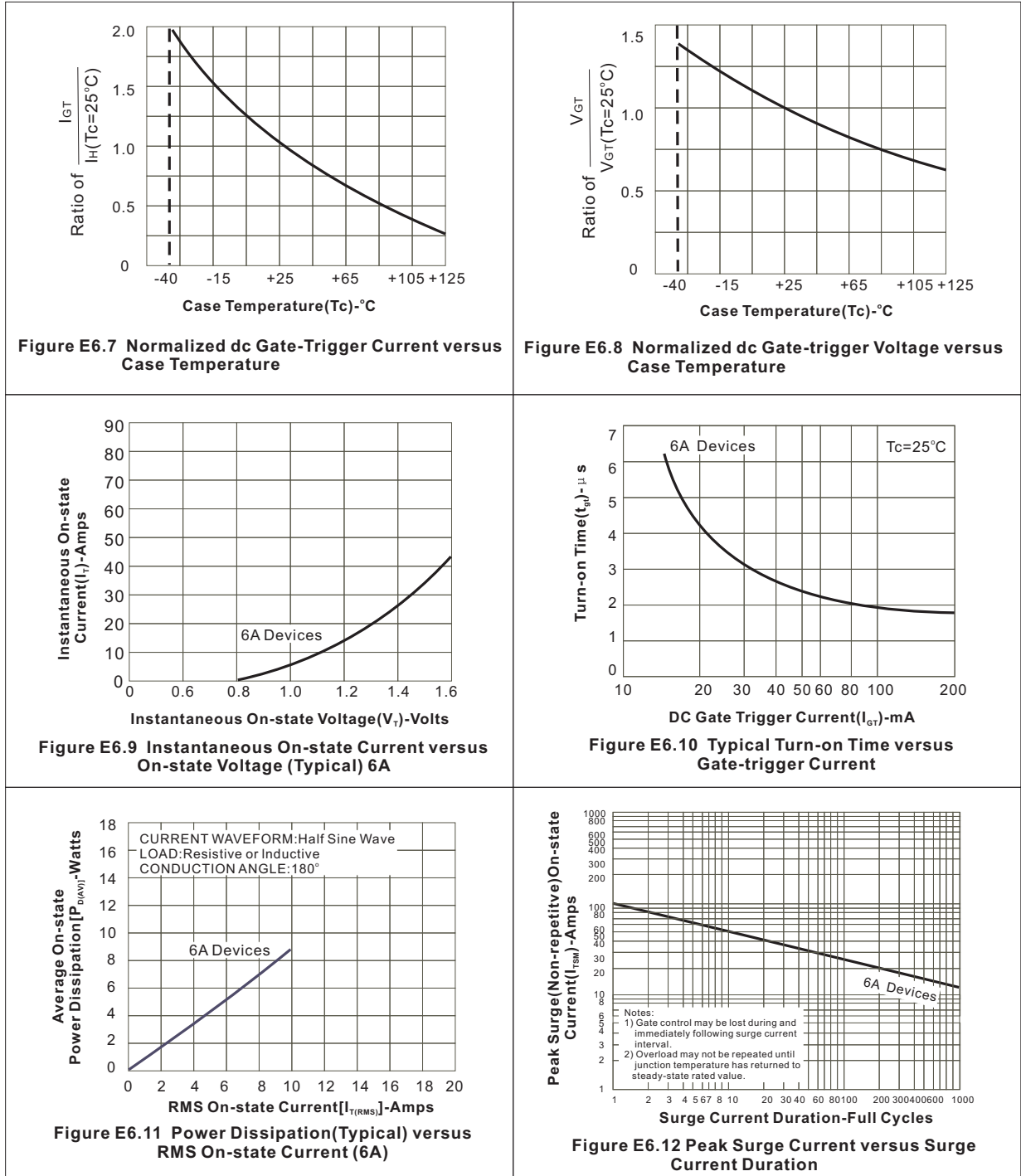
Dynamic Characteristics

D_{vD}/dt	Critical rate of rise of Off-state voltage	$V_{DM}=67\% V_{DRM(max)}$; $T_j=125^\circ\text{C}$; Exponential wave form; $R_{GK}=100\ \Omega$	50	100	-	V/ μ s
t_{gt}	Gate controlled turn-on time	$I_{TM}=10A; V_D=V_{DRM(max)}$; $I_G=5mA$; $DI_G/dt=0.2A/\mu$ s	-	2	-	μ s
t_g	Crcuit commutated turn-off time	$V_{DM}=67\% V_{DRM(max)}$; $T_j=125^\circ\text{C}; I_{TM}=12A$ $V_R=24V; di_{TM}/dt=10A/\mu$ S $dv_{D}/dt=2V/\mu$ s; $R_{GK}=1k\ \Omega$	-	100	-	μ s

Description



Description



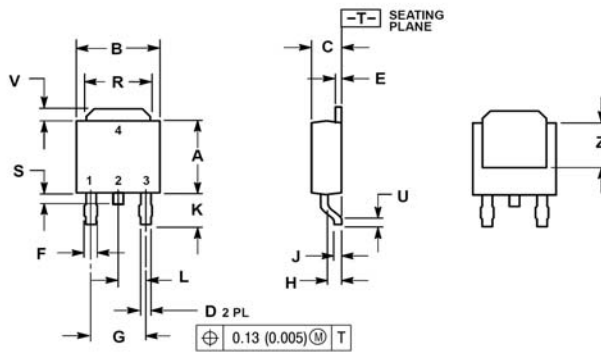
MECHANICAL DATA

Dimensions in mm

Net Mass: 0.45g

TO-252(DPAK)

DPAK
CASE 369C
ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

STYLE 6:

- PIN 1. MT1
- 2. MT2
- 3. GATE
- 4. MT2

SOLDERING FOOTPRINT*

